

PRELIMINARY SPEC

Features:

- HIGH LUMINANCE OUTPUT.
- DESIGN FOR HIGH CURRENT OPERATION.
- UNIFORM COLOR.
- LOW POWER CONSUMPTION.
- LOW THERMAL RESISTANCE.
- LOW PROFILE.
- PACKAGED IN TUBES FOR USE WITH AUTOMATIC INSERTION EQUIPMENT.
- SOLDERING METHODS: WAVE SOLDERING.
- RoHS COMPLIANT.

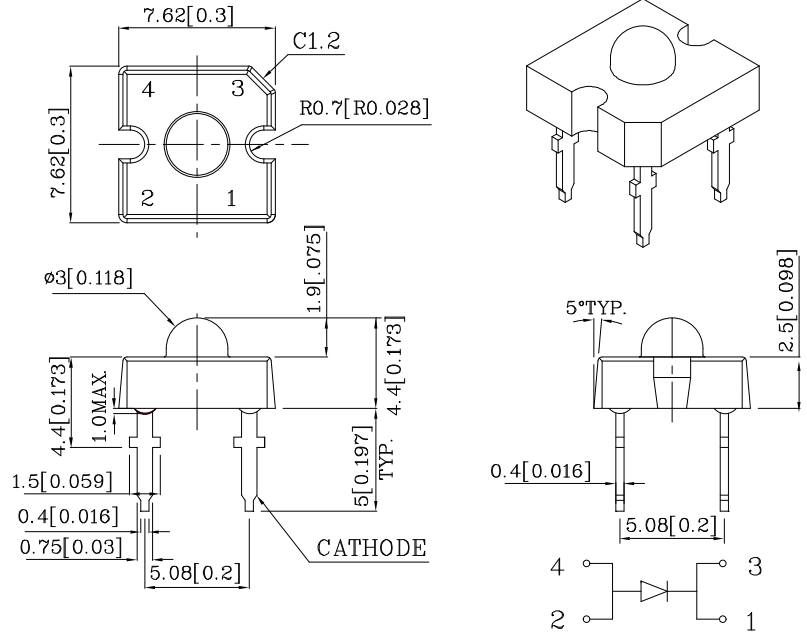


Benefits:

- *Outstanding Material Efficiency.
- *Electricity savings.
- *Maintenance savings.
- *Reliable and Rugged.

Typical Applications:

- *Automotive Exterior Lighting.
- *Electronic Signs and Signals.
- *Specialty Lighting.



Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is $\pm 0.25(0.01")$ unless otherwise noted.
3. Specifications are subject to change without notice.

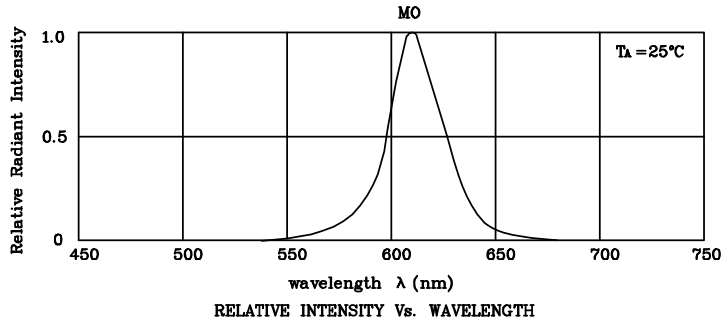
Absolute maximum ratings (TA=25°C)		MO (InGaAlP)	Unit
Reverse Voltage	VR	5	V
Forward Current	IF	70	mA
Power Dissipation	PT	189	mW
Operating Temperature	TA	-40 ~ +85	°C
Storage Temperature	Tstg	-55 ~ +85	
Lead Solder Temperature [1.5mm(0.06inch)Below Seating Plane.]	260°C For 5 Seconds		

1.No Reflow soldering .

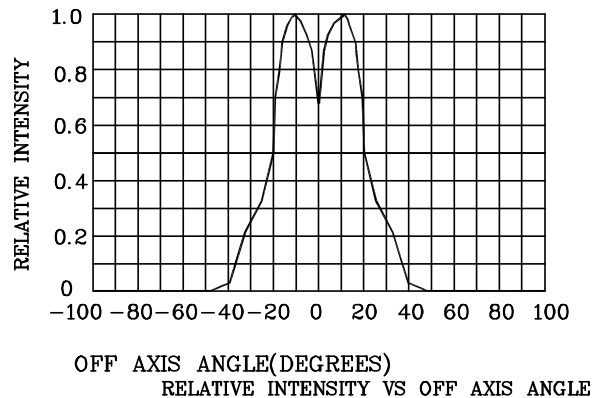
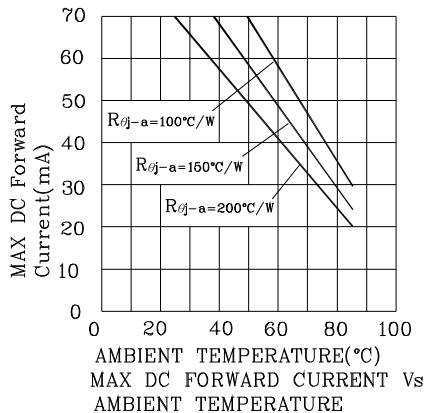
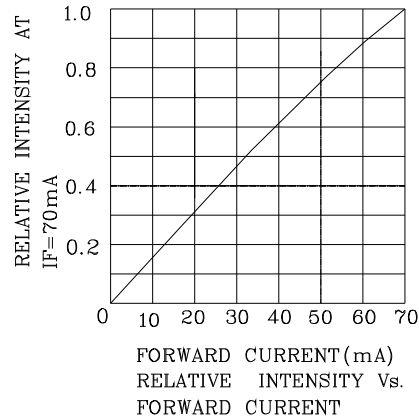
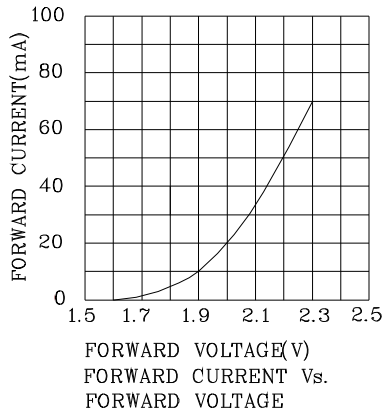
Operating Characteristics (TA=25°C)		MO (InGaAlP)	Unit
Forward Voltage (Typ.) (IF=70mA)	VF	2.3	V
Forward Voltage (Max.) (IF=70mA)	VF	2.7	V
Reverse Current(Max.) (VR=5V)(Typ.)	IR	10	uA
Wavelength of Peak Emission(Typ.) (IF=70mA)	λP	610	nm
Wavelength of Dominant Emission(Typ.) (IF=70mA)	λD	601	nm
Spectral Line Full Width At Half-Maximum(Typ.) (IF=70mA)	$\Delta\lambda$	29	nm
Capacitance(Typ.) (VF=0V, f=1MHz)	C	30	pF
Thermal Resistance	R θ j-pin	125	°C/W

Part Number	Emitting Color	Emitting Material	Lens-color	Luminous Intensity (IF=70mA) mcd		Luminous Flux (IF=70mA) (mlm)	Wavelength nm λ P	Viewing Angle 2θ 1/2
				min.	typ.	typ.		
XSMO883W	Orange	InGaAlP	Water Clear	1800	3990	1500	610	40°

1. LUMINOUS INTENSITY IS MEASURED WITH AN INTEGRATING SPHERE AFTER THE DEVICE HAS STABILIZED.
2. θ 1/2 IS THE ANGLE FROM OPTICAL CENTERLINE WHERE THE LUMINOUS INTENSITY IS 1/2 THE OPTICAL CENTERLINE VALUE.

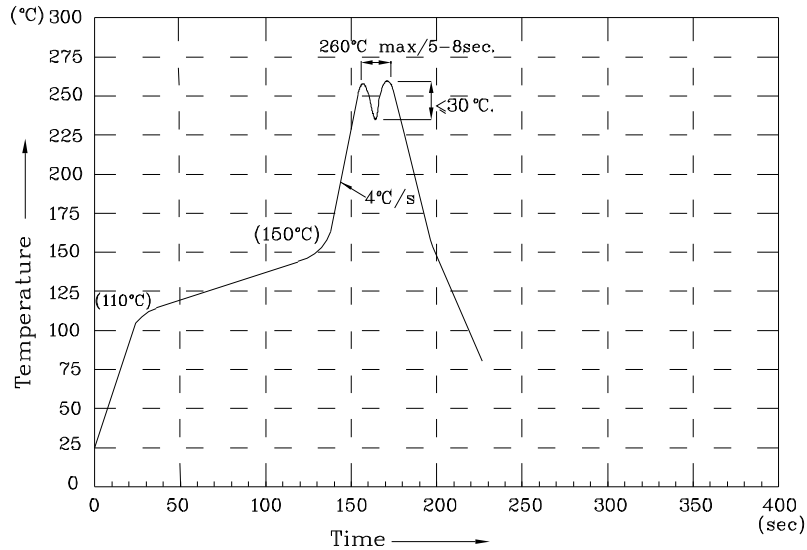


❖ MO



XSMO883W

Wave Soldering Profile For Lead-free Through-hole LED.



NOTES:

1. Recommend the wave temperature 245°C~260°C. The maximum soldering temperature should be less than 260°C.
2. Do not apply stress on epoxy resins when temperature is over 85 degree°C.
3. The soldering profile apply to the lead free soldering (Sn/Cu/Ag alloy).
4. No more than once.

Remarks:

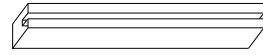
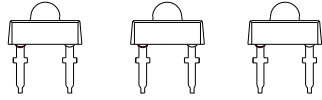
If special sorting is required (e.g. binning based on forward voltage, Luminous intensity / luminous flux, or wavelength), the typical accuracy of the sorting process is as follows:

1. Wavelength: +/-1nm
2. Luminous intensity / luminous flux: +/-15%
3. Forward Voltage: +/-0.1V

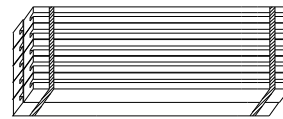
Note: Accuracy may depend on the sorting parameters.



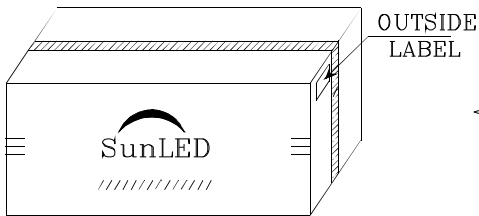
PACKING & LABEL SPECIFICATIONS XSMO883W



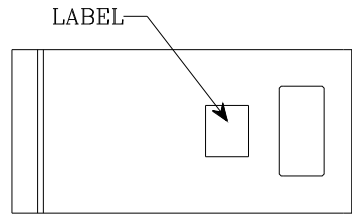
75PCS / IC TUBE(520x8.3x15mm)




750pcs / 10pcs IC TUBE




7.5K / BOX



10pcs IC TUBE / Bag



Q.C. Q C
XX XX XXXX
PASSED

P/NO : XSxxx883x	
QTY : 750 pcs	CODE: XXX
S/N : XX	
LOT NO:	
 xxxxxxxxxxxxxxxxxxxxxxxx	
RoHS Compliant	